

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	76680	439/\$.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:00
2	BRS	L2	94344	361/\$.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:00
3	BRS	L3	165209	1 or 2	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:00
4	BRS	L4	25815	3 and layers	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:01
5	BRS	L5	12225	4 and (heat or thermal)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:01

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	9164	5 and contact	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:02
7	BRS	L7	6483	6 and plurality	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:02
8	BRS	L8	4455	7 and (insulating or dielectric)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:03
9	BRS	L9	3087	8 and (holes or apertures)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:04
10	BRS	L10	1323	9 and (liner or plated)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L11	1225	10 and (PCB or board or substrate)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:06
12	BRS	L12	1161	11 and electrical	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:06
13	BRS	L13	1149	12 and (conduct\$3 or dissipat\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:07
14	BRS	L14	1151	12 and (conduct\$3 or dissipat\$3 or spread\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:08
15	BRS	L15	727	12 and ((heat or thermal) with (conduct\$3 or dissipat\$3 or spread\$3))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/12/13 12:09